

SSC8L412PN6

N-Channel Enhancement Mode MOSFET

> Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	l _D
40V	±20V	1.4 mΩ@10V	170A
		2.1 mΩ@4.5V	ITUA

Description

This device is N-Channel enhancement MOSFET.

Uses SGT technology and design to provide excellent

RDSON with low gate charge. This device is suitable
for use in DC-DC conversion, power switch and
charging circuit.

100% UIS + ΔVDS + Rg Tested!

Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

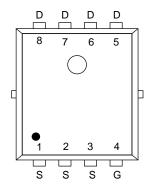
Ordering Information

Device	Package	Shipping		
SSC8L412PN6	PDFN5X6-8L	5000/Reel		

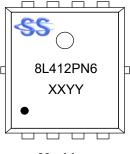
> Pin Configuration



PDFN5X6-8L



Pin Configuration (Top View)



Marking

(XXYY: Internal Traceability Code)



➤ Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit		
V_{DSS}	Drain-to-Source Volta	40	V		
V _{GSS}	Gate-to-Source Volta	Gate-to-Source Voltage			
	Continuous Dusin Comment d	T _C =25℃	170	^	
I D	Continuous Drain Current ^d	T _C =100℃	94	A	
,	Ocation of Design Comment 2	T _A =25℃	27	^	
IDSM	Continuous Drain Current ^a	T _A =70°C	20	A	
I _{DM}	Pulsed Drain Current	679	Α		
Б	Davis Diagingtion (Tc=25°C	83	10/	
P _D	Power Dissipation ^c	Tc=100°C	33	W	
	Davis Diaging tion 2	T _A =25°C	2.1	10/	
P _{DSM}	Power Dissipation ^a	T _A =70°C	1.3	W	
las	Avalanche Current ^b L=0.5mH \$	37	Α		
Eas	Avalanche Energy ^b L=0.5mH \$	342	mJ		
TJ	Operation junction tempe	-55~150	%		
T _{STG}	Storage temperature ra	-55~150	℃		

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Max.	Unit
R _{θJA}	Junction-to-Ambient Thermal Resistance a	44	60	°C/W
R _{θJC}	Junction-to-Case Thermal Resistance	1.0	1.5	C/VV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.



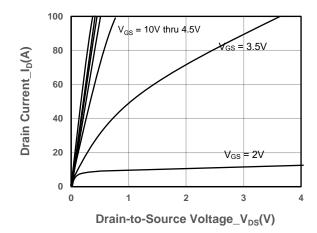


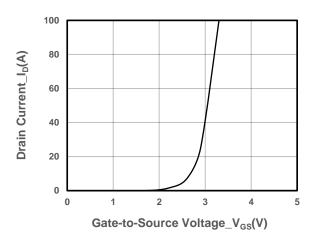
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	40			V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250$ uA	1.0	1.7	2.2	٧	
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		1.4	1.8	mΩ	
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 10A		2.1	2.7	mΩ	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 40V, V _{GS} = 0V			1	μA	
Gate-Source Leak Current	lgss	V _{GS} = ±20V, V _{DS} = 0V			±100	nA	
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 10A		0.7	1.3	V	
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		2.0		Ω	
Input Capacitance	Cıss	V - 20V V - 0V		3243		pF	
Output Capacitance	Coss	$V_{DS} = 20V$, $V_{GS} = 0V$, $f = 1MHz$		1304			
Reverse Transfer Capacitance	C _{RSS}	I – IIVIDZ		94			
Total Gate Charge	Q _G	\\ -40\\\\ -45\\		49			
Gate to Source Charge	Q _G s	$V_{GS} = 10V, V_{DS} = 15V,$ $I_{D} = 20A$		11		nC	
Gate to Drain Charge	Q _{GD}	1D – 20A		7.5			
Turn-on Delay Time	T _{D(ON)}			8.4			
Rise Time	Tr	$V_{GS} = 10V, V_{DS} = 20V, R_L$		8.7			
Turn-off Delay Time	T _{D(OFF)}	= 1Ω , $R_G = 3\Omega$		44		ns	
Fall Time	T _f			26			
Diode Recovery Time	Trr	I _F =20A, di/dt=100A/us		53		ns	
Diode Recovery Charge	Qrr	I _F =20A, di/dt=100A/us		39		nC	



➤ Typical Performance Characteristics (T_A=25°C unless otherwise noted)

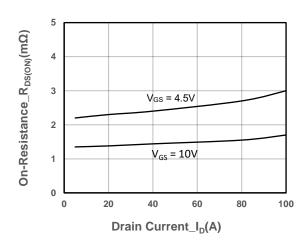


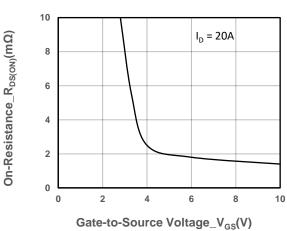


Transfer Characteristics

Output Characteristics

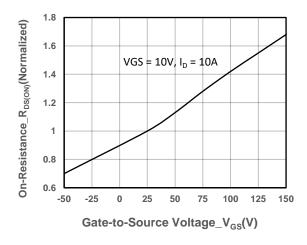


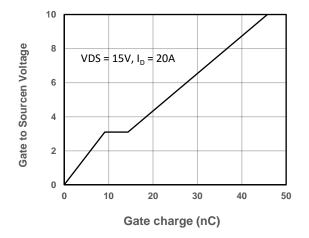




On-Resistance vs. Drain Current and Gate Voltag

On-Resistance vs. Gate-to-Source Voltage

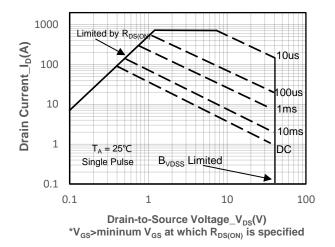




On-Resistance vs. Junction Temperature

Gate-Source Voltage vs. Gate charge

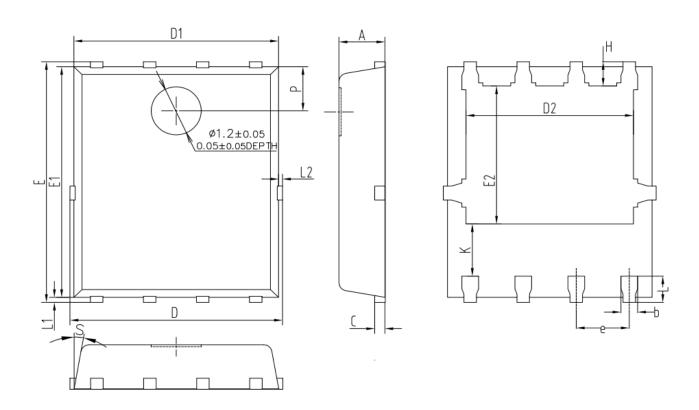




Safe Operating Area vs. Junction-to-Ambient



Package Information



COMMON DIMENSIONS (UNIT of MEASURE=MILLIMETER)											
SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
Α	1.00	1.10	1.20	е	1.17	1.27	1.37	L	0.55	0.65	0.75
b	0.35	0.40	0.45	E	5.90	6.00	6.10	L1	0	0.10	0.15
С	0.19	0.25	0.30	E1	5.70	5.75	5.80	L2	0	0.10	0.15
D	4.80	5.10	5.20	E2	3.35	3.45	3.55	Р	1.00	1.10	1.20
D1	4.80	4.90	5.00	Н	0.50	0.60	0.70	S	8°	10°	12°
D2	3.90	4.00	4.10	K	1.20	1.30	1.40				



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